

US Department of Commerce Patent and Trademark Office Form PTO-1449 (Modified)		Atty. Docket No.: 42390P11370		Application No.: Not Yet Assigned		
		Applicant: Ohfuji et al.		09-965280		
		Filing Date: Concurrently Herewith		09/965280		
US Patent Documents						
Examiner's Initials	Date	Document Number	Name	Class	Sub- Class	Filing Date
SPM	01/02/01	6,169,274 B1	Kulp	—	—	03/01/99
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Examiner's Initials	Date	Document Number	Country	Class	Sub- Class	Translation
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SPM		Section 2.7 Resists, SPIE Handbook of Microlithography, Micromachining and Microfabrication, Volume 1: Microlithography. [online] [retrieved on 8-3-01] Retrieved from the Internet <URL: http://www.cnf.cornell.edu/SPIEBook/spie7.htm Pgs. 1-11				
SPM		Negative e-beam resist SAL603-0.45 [online] [retrieved on 8-3-01] Retrieved from the Internet: <URL: http://www.nanophys.kth.se/nanophys/facilities/nfl/resists/sal603.html Pages 1-3.				
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Examiner Mohamedulla		Date Considered 8/10/04				

Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw a line through the citation if not in conformance and not considered. Include a copy of this form with the next communication to the applicant

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Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)							
		SPIE Volume 1086, Advances In Resists Technology and Processing.(1989) Deep UV ANR Photoresists For 248 nm Excimer Laser Photolithography. James W. Thackeray, George W. Orsula, Edward K. Pavelchek, Dianne Canistro; Shipley Co., Inc., Newton Massachusetts. Leonard E. Bogan Jr., Amanda K. Berry, Karen A. Graziano; Rohm and Hass Co., Inc. Philadelphia Pennsylvania. Pages 34-47.					
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Examiner	Mohamed Ull			Date Considered			8/10/04

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